



Material Content Data Sheet



Sales Product Name		TLE7236EM		Issued		28. August 2013		
MA#		MA000982092						
Package		PG-SSOP-24-4		Weight*		150.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.306	2.85	2.85	28530	28530
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8913	
wire	non noble metal	copper	7440-50-8	54.617	36.19	37.13	361885	371355
	noble metal	gold	7440-57-5	0.572	0.38	0.38	3788	3788
encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1135	
	plastics	epoxy resin	-	7.880	5.22		52212	
	inorganic material	silicondioxide	60676-86-0	77.600	51.42	56.75	514170	567517
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19287	19287
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1552	1552
glue	plastics	epoxy resin	-	0.301	0.20		1993	
	noble metal	silver	7440-22-4	0.902	0.60	0.80	5978	7971
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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